

Benefits of Pulse Plating

METALLURGICAL

- Denser deposit
- Finer grain deposit
- Lower porosity
- Higher tensile strength
- Higher elongation
- Reduced stress
- Reduce hydrogen embrittlement

ELECTRICAL

- Higher conductivity
- Lower contact resistance
- Better bondability

PHYSICAL

- Fills submicron trenches
- Improved adhesion of deposit
- Reduced stress on photo resists
- Increased throwing power
- Control of alloy composition
- Uniform thickness
- Improved chem. milling

GENERAL

- Metal concentration in bath
- Reduce additives
- Reduce plating time 10 - 20%

Dynatronix maintains a library of electroplating papers and [articles](#) covering a variety of metals and applications. Many of these [articles](#) are available in PDF format here on the Dynatronix web site. Please contact us at (800)-826-7172 if you do not find information on the specific topic you are looking for.